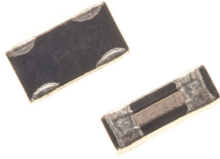


SCCM Series



Features

Powerful components with composite co-fired material to solve EMI problem for high speed differential signal transmission line as USB, and LVDS, without distortion to high speed signal transmission.

Applications

MIPI, MHL serial interface in mobile device

Product Identification

SCCM xxxxxx HSxTL - xxxx

For example: SCCM201210HSHTL-900A

General Specifications

Test Frequency.....100MHz
 Parameters Test Temp.....25℃
 Operation Temp.....-40℃ to +85℃
 (Including temperature Rise)
 Storage Temp.....0~40℃
 Storage Humidity.....<70% RH
 Resistance to Soldering Heat.....260℃ for 10 sec
 Temperature Rise.....40℃ Typ. at Rated Current

Shape And Dimensions

Fig.1

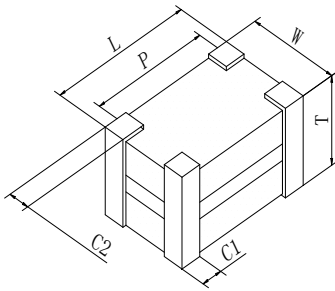
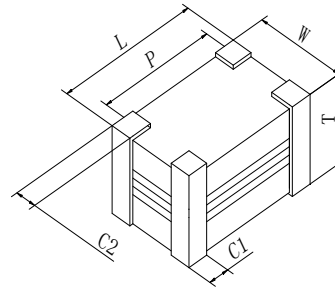
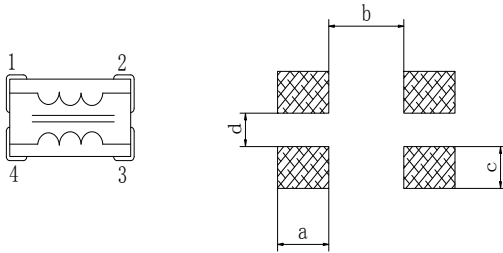


Fig.2



Electrical Schematic & PAD Layout



Shape And Dimensions

TYPE	L	W	T	P	C1	C2	a	b	c	d
		±0.2	±0.2	±0.2	±0.2	±0.2	±0.2	Ref	Ref	Ref
201210	2.00	1.20	1.00	1.60	0.40	0.30	0.75	1.10	0.50	0.40

Standard Specifications

Stamp	Impedance (Ω)(±25%)	Test Frequency (MHz)	DCR (Ω) Max	Rated Current (mA) Max	Rated Voltage (V)	Insulation Resistance(MΩ) Min	Shape
SCCM201210HSHTL-670A	67	100	1.0	200	10	100	Fig.1
SCCM201210HSHTL-900A	90	100	1.0	200	10	100	Fig.1
SCCM201210HSDTL-500A	50	100	1.0	100	10	100	Fig.2
SCCM201210HSDTL-900A	90	100	1.0	200	10	100	Fig.1
SCCM201210HSDTL-121A	120	100	1.2	100	10	100	Fig.1
SCCM201210HSSTL-500A	50	100	1.0	100	10	100	Fig.2

*All the data listed in this catalogue are for reference only, JENG SHI reserves the right to alter or revise the specifications without prior notification.

*Beyond the above specification also can meet the special requirements. Need detailed content Please to the website query or contact us.

